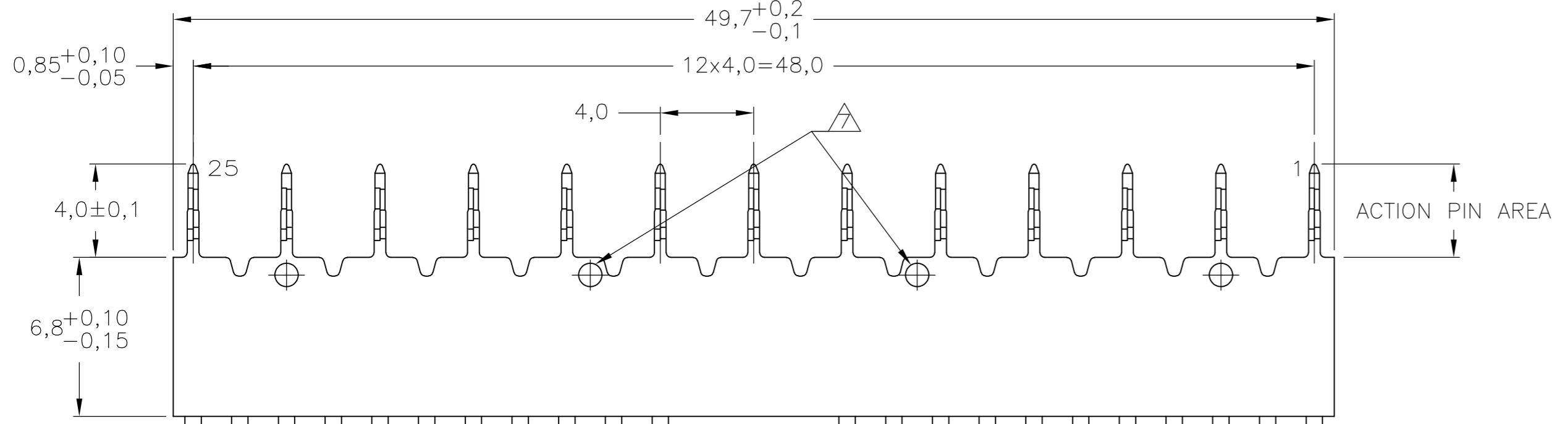


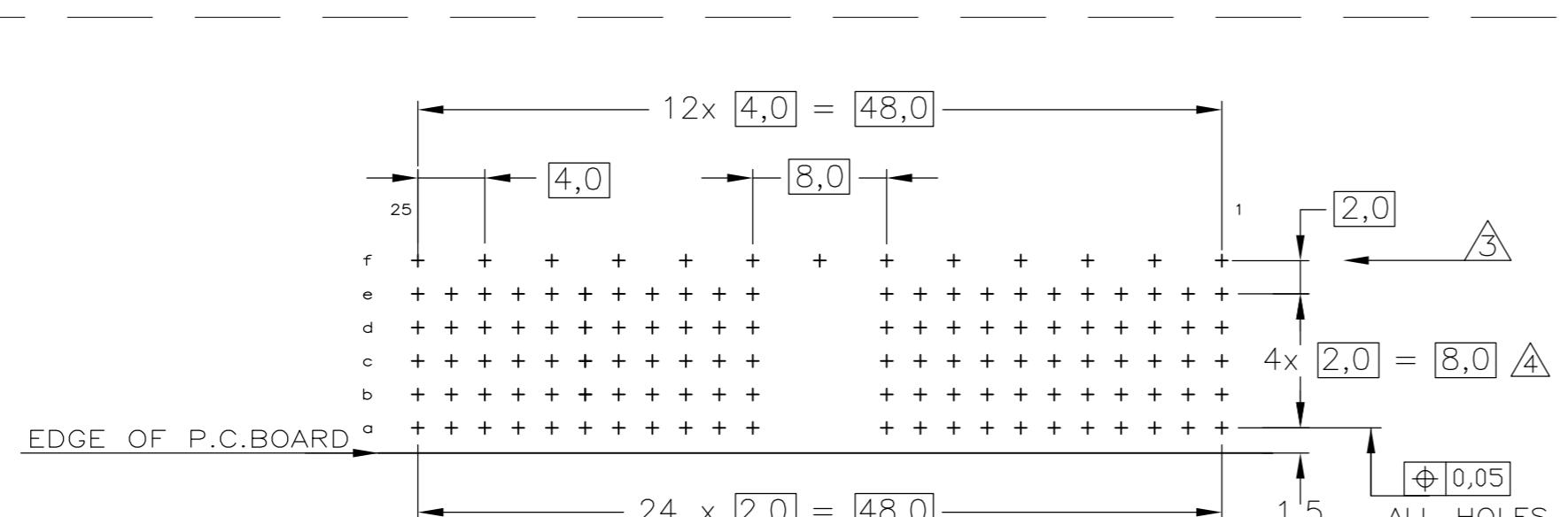
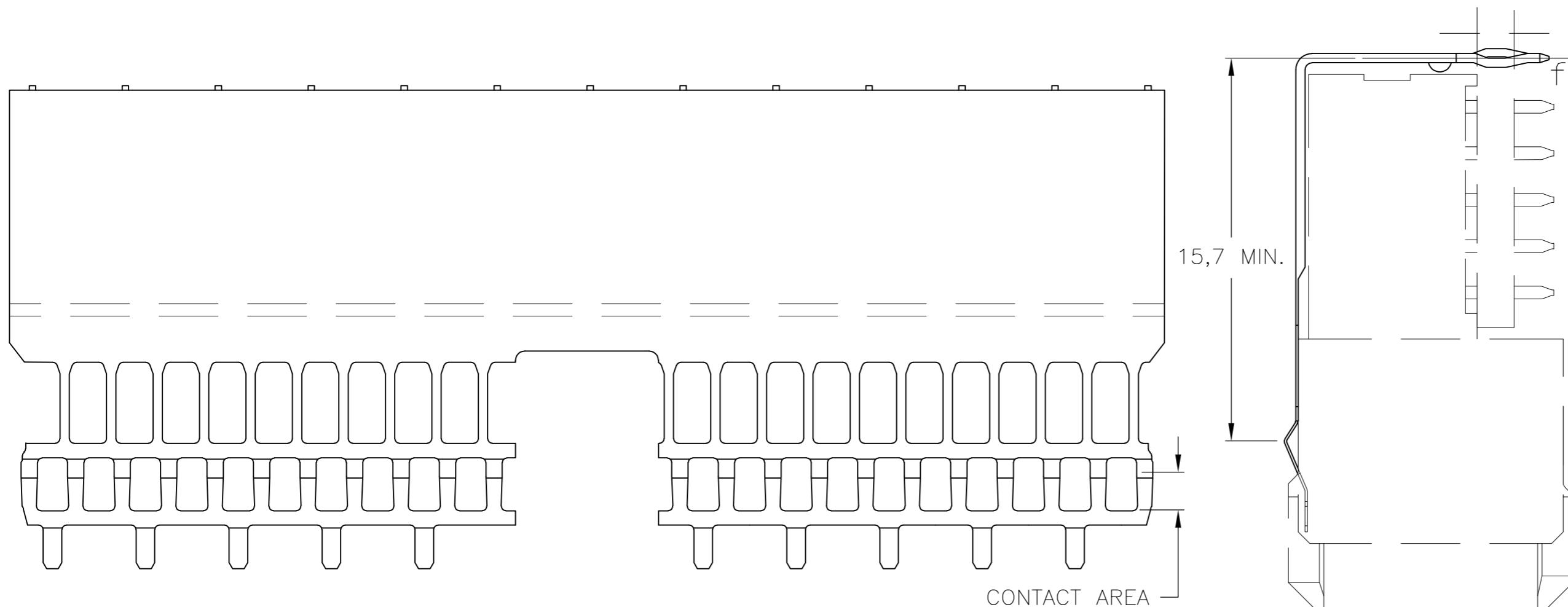
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LOC	DIST	REVISIONS				
		P	LTR	DESCRIPTION	DATE	DWN
ES	00	K		REVISED PER ECO-13-015151	16DEC2013	FL FY



NOTES:

- ▲ GENERAL PLATING SPECIFICATION: UNDERPLATING (ENTIRE CONTACT): 1,27µm NICKEL MIN. AND ACTION PIN: 0,5µm TIN-LEAD MIN. FOR PLATING OF MATING SURFACES SEE PERFORMANCE LEVEL SHOWN IN PART NUMBER TABLE.
- ▲ MATERIAL: PHOSPHORBRONZE.
- ▲ ROW "f" 13 PLATED THROUGH HOLES FOR UPPERSHIELD
- ▲ HOLE PATTERN FOR FEMALE CONNECTOR TYPE A 110 PLATED-THROUGH HOLES AT 2x2mm SQUARE GRID
- ▲ SHIELDS LUBRICATED WITH BELLCORE APPROVED LUBRICANT. TECHNICAL REF: TR-NWT-001217 ISSUE 1, SEPT. 1992.
- ▲ GENERAL PLATING SPECIFICATION: UNDERPLATING (ENTIRE CONTACT): 1,27µm NICKEL MIN. AND ACTION PIN: 0,5µm TIN-LEAD MIN. ASTM B579 60/40 FOR PLATING OF MATING SURFACES SEE PERFORMANCE LEVEL SHOWN IN PART NUMBER TABLE.
- ▲ OPTIONAL DIMPLES AT DISCRETION OF DIE ENGINEER.
- ▲ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI
- ▲ CONFORMS TO ALL TESTING ACCORDING IEC 61076-4-101 PERFORMANCE LEVEL 2.
- ▲ CONFORMS TO ALL TESTING ACCORDING IEC 61076-4-101 PERFORMANCE LEVEL 1.
- ▲ CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR-1217-CORE QUALITY LEVEL III, CENTRAL OFFICE APPLICATIONS.
- ▲ 0.76µm MIN GOLD PLATING AT MATING SURFACE.
- ▲ 1.27µm MIN GOLD PLATING AT MATING SURFACE.



COMPONENT SIDE AS SHOWN  
RECOMMENDED PCB-HOLE LAY-OUT

P.C.B. HOLE DIM. ACTION PIN  
FOR DETAILS SEE  
APPLICATION SPECIFICATION

8	OBSOLETE	1 9 12	8-338107-4
8	OBSOLETE	1 13	9-338107-3
		6 5 11	9-338107-1
		1 5 11	-338107-9
		2	338107-2
		1 9	
		2	MATERIAL
			PARTNUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		28-11-96
D. TRUREN		28-11-96
CHK		W/ v.d.HEIJDEN
APVD		F. v.KONINGSBRUGGE
PRODUCT SPEC		108-19082
APPLICATION SPEC		114-19029
MATERIAL		WEIGHT
CAGE CODE	DRAWING NO	RESTRICTED TO
A2 00779	C-338107	-
CUSTOMER DRAWING		SCALE 5:1
		SHEET 1 OF 1
		REV K